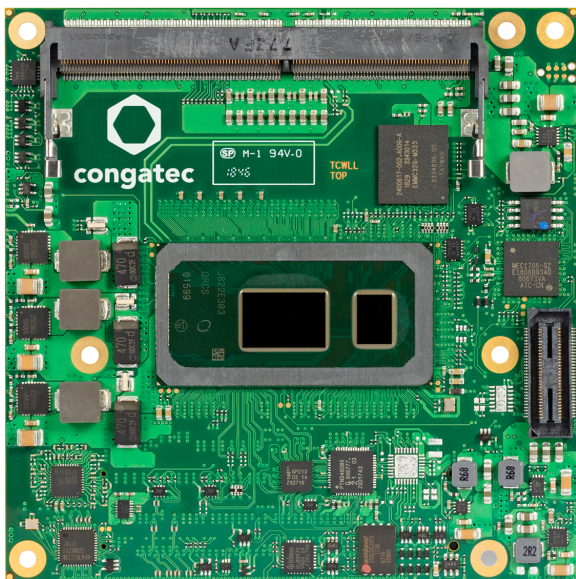


# QUAD CORE COMPACT

## conga-TC370

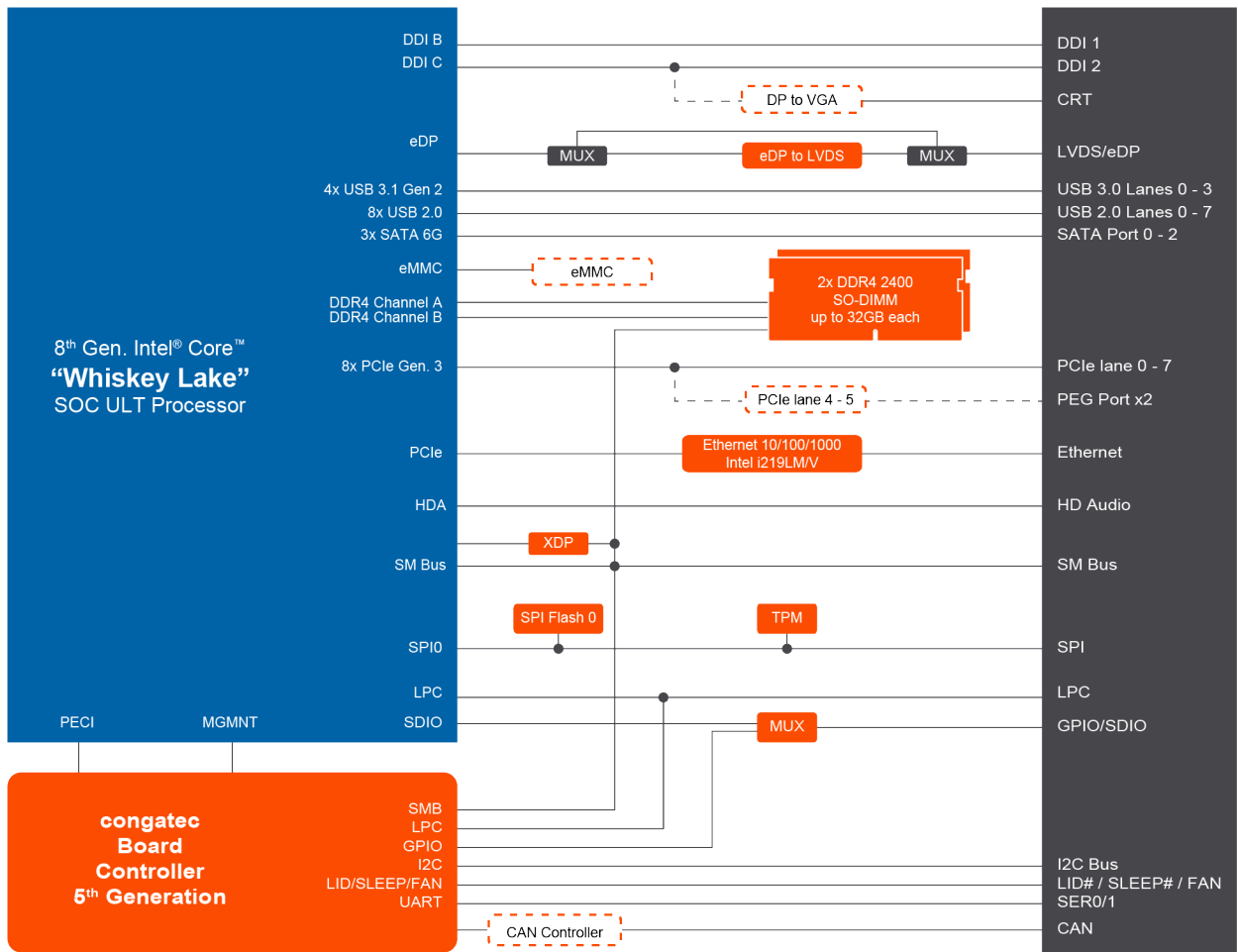



- 8<sup>th</sup> Generation Intel® Core™ SOC processor up to 4 cores
- Configuration of display mode by software (LVDS/eDP)
- Low power consumption (TDP 15W, cTDP 10W)
- Up to 64 GByte dual channel DDR4 2400 MT/s
- Optional eMMC 5.1 on board mass storage
- Trusted Platform Module (TPM 2.0)
- COM Express Compact Type 6 module 95x95 mm<sup>2</sup>



Formfactor	COM Express® Compact, (95 x 95 mm), Type 6 Connector Layout			
CPU	Intel® Core™ i7-8665UE 4.40 GHz (Burst)   1.7 GHz Clock	Quad Core, 8 Threads	L2 cache 8MB	15W TDP (configurable to 10/25W)
	Intel® Core™ i5-8365UE 4.10 GHz (Burst)   1.6 GHz Clock	Quad Core, 8 Threads	L2 cache 6MB	15W TDP (configurable to 10/25W)
	Intel® Core™ i3-8145UE 3.90 GHz (Burst)   2.2 GHz Clock	Dual Core, 4 Threads	L2 cache 4MB	15W TDP (configurable to 10/25W)
	Intel® Celeron® 4305UE 2.00 GHz (Burst)   2.0 GHz Clock	Dual Core, 2 Threads	L2 cache 2MB	15W TDP
DRAM	Dual channel DDR4 up to 2.400 MT/s   2x SO-DIMM   max. 2x 32 Gbyte			
Chipset	Integrated Intel® 300 Series			
Ethernet	1x Gigabit Ethernet   Intel i219LM			
Sound	Digital High Definition Audio Interface with support for multiple audio codecs			
Graphics	Intel® Gen9 HD Graphics Engine with OpenCL 2.1, OpenGL 4.5 and DirectX12 (for Windows 10) support   up to three independent displays   High performance hardware MPEG-2 decoding   WMV9 (VC-1) and H.265 (HEVC) support Blu-ray support @ 40 MBit/s   HEVC and VP9 encoding			
Display Interface	2x DDI   18/24bit single/dual channel LVDS or eDP   optional VGA interface   LVDS interface with optional eDP overlay. Configuration of display mode by software			
I/O Interfaces	8x PCI Express Gen 3.0 lanes   3x Serial ATA Gen 3 (can be configured as RAID)   4x USB 3.1 Gen 2   8x USB 2.0   LPC bus (no DMA)   I <sup>2</sup> C bus (fast mode, 400 kHz, multi-master)   2x UART			
Storage	optional eMMC 5.1 on board mass storage			
congatec Board Controller	Multi Stage Watchdog   non-volatile User Data Storage   Manufacturing and Board Information   Board Statistics   I <sup>2</sup> C bus (fast mode, 400 kHz, multi-master)   Power Loss Control   Hardware Health Monitoring   POST Code redirection			
Embedded BIOS Features	AMI Aptio® 2.X (UEFI) BIOS   SM-BIOS   BIOS Update   Logo Boot   Quiet Boot   HDD Password			
Security	Trusted Platform Module (TPM 2.0)   Secure Root of Trust   Secure Memory Encryption   Secure Encrypted Virtualization			
Power Management	ACPI compliant with battery support   Suspend to RAM (S3) support   S5 enhanced support   Intel AMT 12.0 support			
Operating Systems	Microsoft® Windows 10 (64bit only)   Microsoft® Windows 10 IoT Enterprise (64bit only)   Linux			
Power Consumption	See user's guide for full details			
Temperature	Operating: 0 .. +60°C Storage: -20 .. +70°C			
Humidity	Operating: 10 - 90% r. H. non cond. Storage: 5 - 95% r. H. non cond.			
Size	95 x 95 mm (3.74" x 3.74")			

# conga-TC370 | Block diagram



 Optional - Not available by default

# conga-TC370 | Order Information

Article	PN	Description
conga-TC370/i7-8665UE	048800	COM Express Type 6 Compact module with Intel® Core™ i7-8665UE quad core processor with 1.7GHz, 8MB L2 cache, GT2 graphics and 2400MT/s dual channel DDR4 memory interface (15W).
conga-TC370/i5-8365UE	048801	COM Express Type 6 Compact module with Intel® Core™ i5-8365UE quad core processor with 1.6GHz, 6MB L2 cache, GT2 graphics and 2400MT/s dual channel DDR4 memory interface (15W).
conga-TC370/i3-8145UE	048802	COM Express Type 6 Compact module with Intel® Core™ i3-8145UE dual core processor with 2.2GHz, 4MB L2 cache, GT2 graphics and 2400MT/s dual channel DDR4 memory interface (15W).
conga-TC370/4305UE	048804	COM Express Type 6 Compact module with Intel® Celeron® Processor 4305UE, dual core with 2.0GHz, 2MB L2 cache, GT1 graphics and 2400MT/s dual channel DDR4 memory interface (15W).
conga-TC370/CSA-HP-B	048850	Standard active cooling solution for COM Express Compact modules conga-TC370 with integrated heat pipes, 25.5mm overall cooling height and integrated 12V fan. Through hole mounting with bore hole standoffs Ø2.7mm.
conga-TC370/CSA-HP-T	048851	Standard active cooling solution for COM Express Compact modules conga-TC370 with integrated heat pipes, 25.5mm overall cooling height and integrated 12V fan. Threaded mounting with threaded standoffs M2.5.
conga-TC370/CSP-HP-B	048852	Standard passive cooling solution for COM Express Compact modules conga-TC370 with integrated heat pipes and 24.3mm overall cooling height. Through hole mounting with bore hole standoffs Ø2.7mm.
conga-TC370/CSP-HP-T	048853	Standard passive cooling solution for COM Express Compact modules conga-TC370 with integrated heat pipes and 24.3mm overall cooling height. Threaded mounting with threaded standoffs M2.5.
conga-TC370/HSP-HP-B	048854	Standard heatspreader for COM Express Compact modules conga-TC370 with integrated heat pipes and 11mm overall cooling height. Through hole mounting with bore hole standoffs Ø2.7mm.
conga-TC370/HSP-HP-T	048855	Standard heatspreader for COM Express Compact modules conga-TC370 with integrated heat pipes and 11mm overall cooling height. Threaded mounting with threaded standoffs M2.5.
DDR4-SODIMM-2400 (4GB)	068790	DDR4 SODIMM memory module with 2400 MT/s and 4GB RAM
DDR4-SODIMM-2400 (8GB)	068791	DDR4 SODIMM memory module with 2400 MT/s and 8GB RAM
DDR4-SODIMM-2400 (16GB)	068792	DDR4 SODIMM memory module with 2400 MT/s and 16GB RAM
DDR4-SODIMM-2400 (32GB)	068809	DDR4 SODIMM memory module with 2400 MT/s and 32GB RAM
DDR4-SODIMM-2666 (4GB)	067780	DDR4 SODIMM memory module with 2666 MT/s and 4GB RAM
DDR4-SODIMM-2666 (8GB)	067781	DDR4 SODIMM memory module with 2666 MT/s and 8GB RAM
DDR4-SODIMM-2666 (16GB)	067782	DDR4 SODIMM memory module with 2666 MT/s and 16GB RAM
DDR4-SODIMM-2666 (32GB)	068806	DDR4 SODIMM memory module with 2666 MT/s and 32XGB RAM
<b>Accessories</b>		
conga-TEVAL	065810	Evaluation carrier board for Type 6 COM-Express-modules
conga-LDVI/EPI	011115	LVDS to DVI converter board for digital flat panels with onboard EEPROM